



PATENT  
Docket No.: 1133/201

**CERTIFICATE OF MAILING OR TRANSMISSION**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 or being facsimile transmitted to the USPTO (571) 273-8300 on January 14, 2008.

Julie Nguyen

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In the application of:

Kahner, et al.

Serial No.: 10/676,908

Filing Date: September 30, 2003.

For: ABATEMENT OF CONTAMINATION  
PRESENT IN STRUCTURES

Examiner: Joyner, Kevin

Group Art Unit: 1744

**DECLARATION OF JAMES L. UNMACK UNDER 37 CFR § 1.131**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

I, JAMES L. UNMACK, declare as follows:

1. I am one of the co-inventors of the above-captioned U.S. Patent Application ("Patent Application").
2. My co-inventors and me assigned the Patent Application to Innovative Mold Solutions, LLC ("IMS").

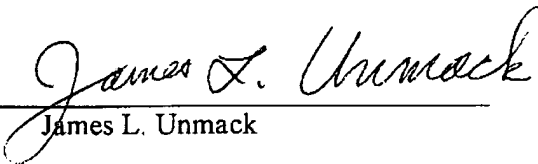
3. Prior to October 8, 2002, I was in discussions with the other co-inventors Alfred A. Kahner, III and Stephen W. Roy, and the President of IMS, Philip Graves, concerning exploitation of the subject matter of the Patent Application.

4. I jointly prepared in consultation with the other co-inventors a one-page written disclosure dated September 30, 2002, of a certain aspect of the subject matter of the Patent Application. Attached as Exhibit A is a true copy of a printout of the written disclosure.

I declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed by me to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the Patent Application or any patent issued thereon.

Executed this 14<sup>th</sup> day of January, 2008 at RANCHO PALMS VERDES, California.

Respectfully submitted,

  
James L. Unmack

Attachment:

Exhibit A

September 30, 2002

A novel method for control of mold infections in voids in structures utilizing microwave energy and adhesives.

Current methodologies require complete removal of infected materials such as drywall to eliminate mold in infected structures. This requires engineered isolation techniques to prevent inadvertent dispersal of mold spores or volatile organic compounds. The current methods are expensive and disruptive for both owners and tenants.

This method involves first heating, in situ, the suspect or identified moldy area with a directed beam of microwave energy to kill the active mold. The energy is applied to the microwave device after a small hole or holes have been made adjacent to the moldy area and a HEPA vacuum has been attached and the vacuum has been started to create a negative air condition in the void. The HEPA vacuum is utilized to remove any sporation or voc's that are released when the microwave begins to heat the mold infected area.

After sufficient temperature to kill the mold has been applied to the area an adhesive is applied by spray, foam or fogging the interior of the wall void through the hole or holes previously made. This adhesive acts to bond any spores still remaining in the void to the existing surfaces thereby minimizing future spore release and the attendant allergen potential.

James Unmack  
Alfred Kahner  
Stephen Roy

EXHIBIT " A "